



SECOND ANNOUNCEMENT AND CALL FOR PAPERS

Sponsored by the Japan Society of Applied Physics and the IEEE Electron Devices Society
In Cooperation with the IEEE Solid-State Circuits Society

2011 SYMPOSIUM ON VLSI TECHNOLOGY

Rihga Royal Hotel Kyoto, Kyoto, Japan

Monday - Thursday, June 13 - 16, 2011

(June 13 Short Course, June 14 - 16 Technical Sessions)

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Local Arrangements:

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Panasonic Corp.

Short Course Organizers:

Satoshi Inaba (Japan)
Toshiba Corp.

Mukesh Khare (USA)
IBM

The 2011 Symposium on VLSI Technology welcomes paper submissions on all aspects of VLSI technology. Not only the field of “**More Moore**” but also implementable “**Beyond CMOS**” as well as “**More than Moore**” technologies are to be covered. **The scopes are being expanded into innovative areas such as:**

- New concepts and breakthroughs in VLSI processes and devices including Memory, Logic, I/O, and I/F (RF/Analog/Mixed-Signal/High-Voltage, Imager, MEMS, etc.)
- Advanced gate stacks and interconnects in VLSI processes and devices
- Advanced lithography and fine-patterning technologies for high-density VLSI
- New functional devices beyond CMOS with a path for VLSI implementation
- Packing of VLSI devices including 3D-system integration
- Advanced device analysis, materials and modeling for VLSI
- Reliability related to the above devices
- Theories and fundamentals related to the above devices
- New concepts and technologies for VLSI manufacturing
- Design enablement (including technology and circuit design interactions in advanced CMOS nodes)
- Heterogeneous integration of non-Si substrates/materials on Si substrate

FOCUS SESSIONS

In 2011 VLSI symposium, two Focus Sessions regarding **Design Enablement including innovations in the field of design for manufacturing and robustness**, and **3D LSI** will be established.

LATE NEWS

In 2011 VLSI symposium, we invite you to submit late news abstracts announcing very recent pioneering results. Deadline for the late news submission is March 24. Submitted papers will be reviewed promptly by all Program Committee members and a very limited number of late news papers will be accepted. Submission procedure will be announced on the 2011 VLSI Symposia website.

VLSI TECHNOLOGY SHORT COURSE

A one-day short course will be held on June 13, 2011. Details will be given in the VLSI Technology Symposium Advance Program, which will be posted on the web by the middle of April, 2011.

SATELLITE WORKSHOPS

2011 Silicon Nanoelectronics Workshop will be held on June 12-13, 2011 as a satellite workshop at the same location where the Symposium takes place. **In addition, 2011 Spintronics Workshop on LSI will be held on June 13 at the same location.**

SUBMISSION OF PAPERS

Prospective authors must upload their submission in the format of two pages of camera-ready paper to <http://www.vlssymposium.org>

The technical content of the accepted paper must not be announced, published, or in any way put in the public domain prior to the Symposium.

Paper Submission Deadline is 17:00 (JST), January 24, 2011

BEST STUDENT PAPER AWARD

The selection will be based upon the quality of the paper and the presentation. The student who receives the Best Student Paper Award will be presented a financial prize and a certificate at the opening session of the 2012 Symposium. For a paper to be reviewed for this Award, the student must be the leading author and the presenter of the paper, and must indicate in the web submission form that the paper is a student paper.

Following the first day of this Symposium, the 2011 Symposium on VLSI Circuits will be held at the same location with two days of overlap between the two symposia. See the reverse side.

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